

Process Change Notification

MSL I Product Moisture Bagging Process

Date:	February 26, 2007	PCN Number: PCN-022607-MCB
Affected Products	All Tantalum MnO ₂ surface mount products, including T49x, T510, B45x products currently packaged in moisture barrier bags (MBB).	
Change Description	KEMET will eliminate air evacuation prior to heat sealing of moisture barrier bags (MBB) used to package the affected products identified above. Use of humidity indicator cards (HIC) and MBB will continue for all products currently packaged in this manner.	
Justification and Benefits	<p>The process modification is in alignment with J-STD-033B.1, Revised January, 2007: Handling, Packing, Shipping and Use of Moisture / Reflow Sensitive Surface Mount Devices. Section 3.3.4 of that standard does not require full air evacuation and in fact warns against the practice due to the resulting potential for diminished dessicant function and / or rupture of the MBB.</p> <p>All affected products are rated MSL level I, defined as not moisture sensitive. Dry packaging for these devices is optional per J-STD-033B.1, Table 3-1. KEMET continues to provide beyond the required moisture protection for these components and elimination of the air evacuation is considered a low risk change.</p>	
Effective Date and Identification	KEMET will begin transition from air evacuation of the affected products effective March 15, 2007. Completion is planned by August 1, 2007. Current product identification will not change.	
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